

Sub F1
E1

1. (Twice Amended) A multi-layer electrode for an integrated circuit, comprising:
a conductive barrier layer;
a first conductive liner disposed over and electrically coupled to the conductive barrier layer;
a second conductive liner disposed over the first conductive liner, the second conductive liner being electrically coupled to the first conductive liner and the conductive barrier layer; and
a conductive layer disposed over the second conductive liner, the conductive layer being electrically coupled to the first conductive liner, the conductive barrier layer and the second conductive liner, wherein the conductive layer and the first conductive liner comprise the same material.

Sub F1
E2

8. (Twice Amended) A multi-layer electrode for an integrated circuit, comprising:
a conductive barrier layer;
a first conductive liner deposited over and abutting the conductive barrier layer, the first conductive liner comprising a molecular grain structure having a plurality of columns;
a second conductive liner deposited over and abutting the first conductive liner, the second conductive liner comprising a conductive oxide; and
a conductive layer deposited over and abutting the second conductive liner, the conductive layer comprising a molecular grain structure having a plurality of columns, wherein the columns of the conductive layer are not aligned with the columns of the first conductive liner.

28. (Twice Amended) An electrode for a semiconductor device, comprising:
a conductive barrier layer;
a platinum liner formed over the conductive barrier layer, the platinum liner comprising a molecular grain structure having a plurality of columns;
a conductive oxide formed over the platinum liner; and
a platinum layer formed over the conductive oxide, the platinum layer comprising a molecular grain structure having a plurality of columns, wherein at least one column of the platinum layer is not aligned with the columns of the platinum liner, wherein the platinum layer is electrically coupled to the platinum liner.

Please add claim 31 as follows:

31. (New) The multi-layer electrode according to Claim 28 wherein the conductive oxide has a thickness of between about 20 and 50 Angstroms.

REMARKS

Claims 1-13, 21-29 and 31, are pending in the present application. Claims 1, 8 and 28 are amended herein and claim 31 is added herein. In view of these amendments and remarks, allowance of the present application is respectfully requested.

Claims 1-13 and 21-30 have been rejected by the Examiner under 35 U.S.C. 103(a) as being unpatentable over Applicants' admitted prior art (AAPA), as shown in the Applicants' Figure 2, in